

1 Characteristics

Table 1. Absolute maximum ratings (limiting values)

Symbol	Parameter			Value	Unit
$I_{T(RMS)}$	RMS on-state current (full sine wave)	D ² PAK, TO-220AB	$T_c = 130\text{ °C}$	16	A
		TO-220AB Ins.	$T_c = 113\text{ °C}$		
I_{TSM}	Non repetitive surge peak on-state current (full cycle, T_j initial = 25 °C)	$f = 50\text{ Hz}$	$t = 20\text{ ms}$	160	A
		$f = 60\text{ Hz}$	$t = 16.7\text{ ms}$	168	
I^2t	I^2t value for fusing		$t_p = 10\text{ ms}$	169	A ² s
di/dt	Critical rate of rise of on-state current, $I_G = 2 \times I_{GT}$, $tr \leq 100\text{ ns}$, $f = 100\text{ Hz}$	$f = 120\text{ Hz}$	$T_j = 150\text{ °C}$	100	A/ μ s
V_{DSM}/V_{RSM}	Non Repetitive peak off-state voltage	$t_p = 10\text{ ms}$	$T_j = 25\text{ °C}$	$V_{DRM}/V_{RRM} + 100$	V
I_{GM}	Peak gate current	$t_p = 20\text{ }\mu$ s	$T_j = 150\text{ °C}$	4	A
$P_{G(AV)}$	Average gate power dissipation		$T_j = 150\text{ °C}$	1	W
T_{stg}	Storage temperature range			-40 to +150	°C
T_j	Operating junction temperature range			-40 to +150	°C

Table 2. Electrical characteristics ($T_j = 25\text{ °C}$, unless otherwise specified)

Symbol	Test conditions	Quadrants		Value		Unit
				T1635H	T1650H	
$I_{GT}^{(1)}$	$V_D = 12\text{ V}$, $R_L = 33\text{ }\Omega$	I - II - III	Max.	35	50	mA
V_{GT}			Max.	1.0		V
V_{GD}	$V_D = V_{DRM}$, $R_L = 3.3\text{ k}\Omega$	I - II - III	Min.	0.15		V
I_L	$I_G = 1.2 \times I_{GT}$	I - III	Max.	50	90	mA
		II	Max.	80	110	
$I_H^{(2)}$	$I_T = 500\text{ mA}$, gate open		Max.	35	75	mA
$dV/dt^{(2)}$	$V_D = 2/3 \times V_{DRM}$, gate open	$T_j = 150\text{ °C}$	Min.	1000	1500	V/ μ s
$(di/dt)_c^{(2)}$	Without snubber	$T_j = 150\text{ °C}$	Min.	21	28	A/ms

1. Minimum I_{GT} is guaranteed at 20% of I_{GT} max.

2. For both polarities of A2 referenced to A1.

Table 3. Static characteristics

Symbol	Test conditions			Value	Unit
$V_T^{(1)}$	$I_{TM} = 23\text{ A}$, $t_p = 380\text{ }\mu\text{s}$	$T_j = 25\text{ }^\circ\text{C}$	Max.	1.5	V
$V_{TO}^{(1)}$	Threshold voltage	$T_j = 150\text{ }^\circ\text{C}$	Max.	0.80	V
$R_{D^{(1)}}$	Dynamic resistance	$T_j = 150\text{ }^\circ\text{C}$	Max.	23	m Ω
$I_{DRM}/$ $I_{RRM}^{(2)}$	$V_{DRM} = V_{RRM}$	$T_j = 25\text{ }^\circ\text{C}$	Max.	5	μA
		$T_j = 150\text{ }^\circ\text{C}$		4.1	mA
	$V_D = V_R = 400\text{ V}$, peak voltage	$T_j = 150\text{ }^\circ\text{C}$	Max.	3.5	mA
	$V_D = V_R = 200\text{ V}$, peak voltage	$T_j = 150\text{ }^\circ\text{C}$	Max.	3.0	

1. For both polarities of A2 referenced to A1.

2. $t_p = 380\text{ }\mu\text{s}$

Table 4. Thermal resistance

Symbol	Parameter		Value	Unit
$R_{th(j-c)}$	Junction to case (AC)	D ² PAK, TO-220AB	1.15	$^\circ\text{C/W}$
		TO-220AB Ins.	2.1	
$R_{th(j-a)}$	Junction to ambient ($S_{cu} = 2\text{ cm}^2$)	D ² PAK, TO-220AB	45	$^\circ\text{C/W}$
	Junction to ambient	TO-220AB Ins.	60	

1.1 Characteristics (curves)

Figure 1. Maximum power dissipation versus on-state RMS current

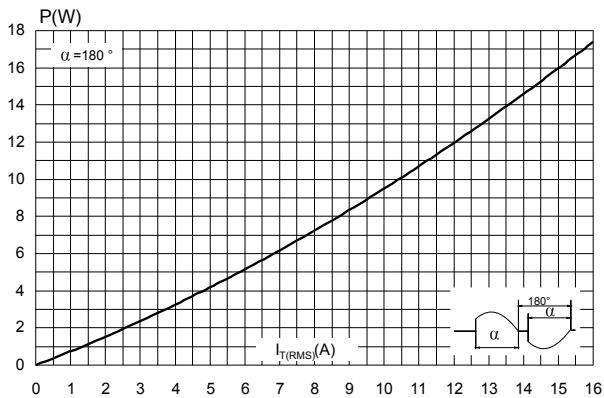


Figure 2. On-state RMS current versus case temperature

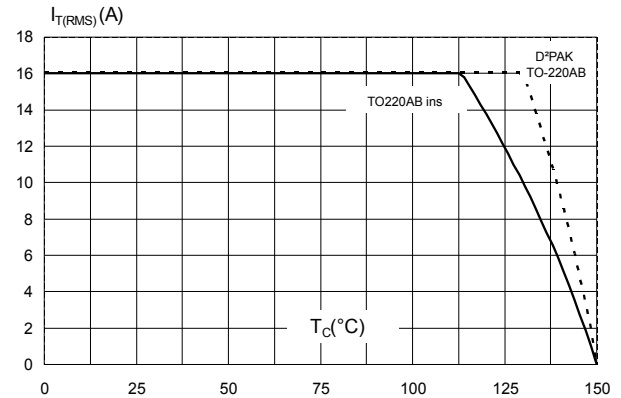


Figure 3. On-state RMS current versus ambient temperature

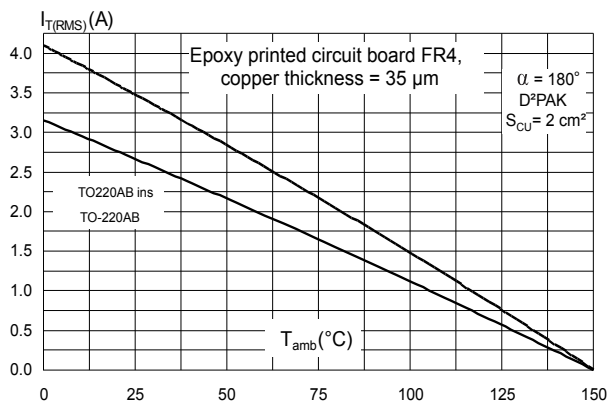


Figure 4. Variation of thermal impedance versus pulse duration

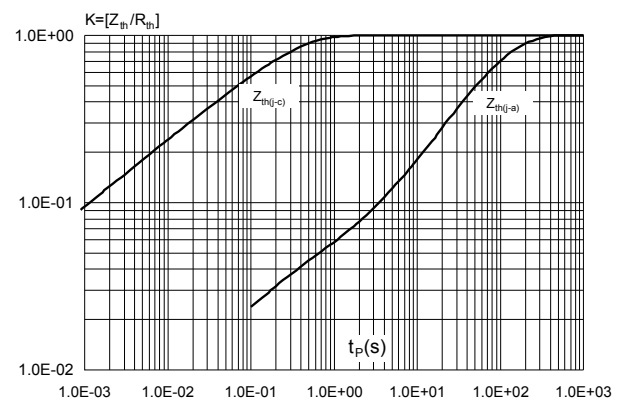


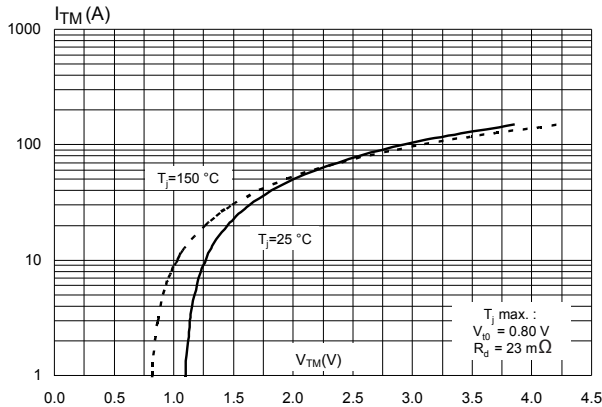
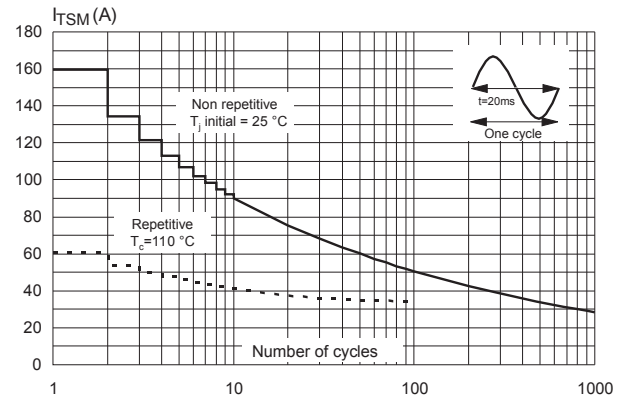
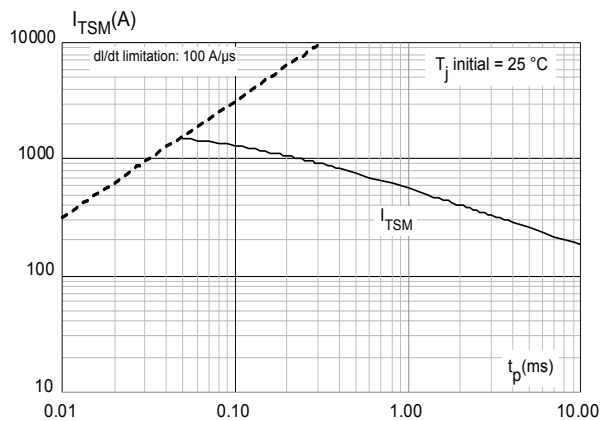
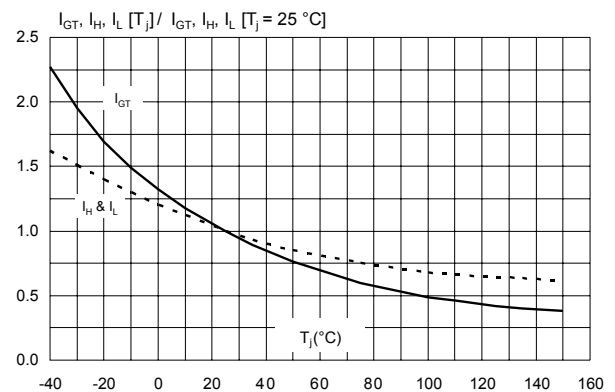
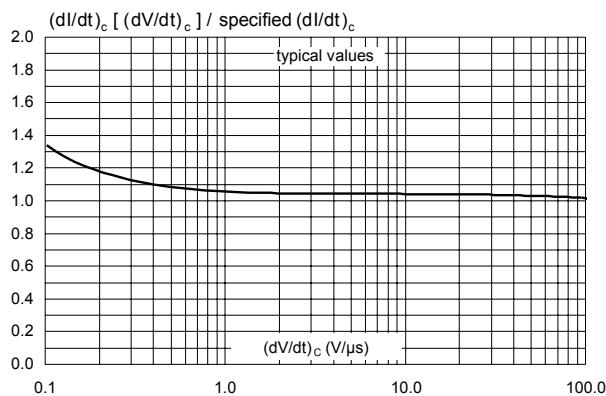
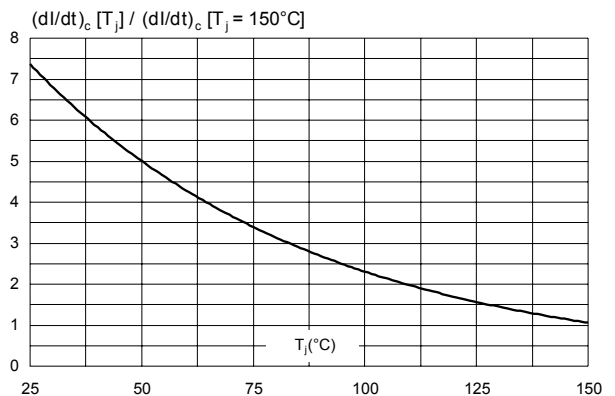
Figure 5. On-state characteristics (maximum values)

Figure 6. Surge peak on-state current versus number of cycles

Figure 7. Non repetitive surge peak on-state current for a sinusoidal pulse with width $t_p < 10$ ms

Figure 8. Relative variation of I_{GT} , I_H , I_L vs junction temperature (typical values)

Figure 9. Relative variation of critical rate of decrease of main current $(di/dt)_c$ versus reapplied $(dV/dt)_c$

Figure 10. Relative variation of critical rate of decrease of main current versus junction temperature


Figure 11. Leakage current versus junction temperature for different values of blocking voltage (typical values)

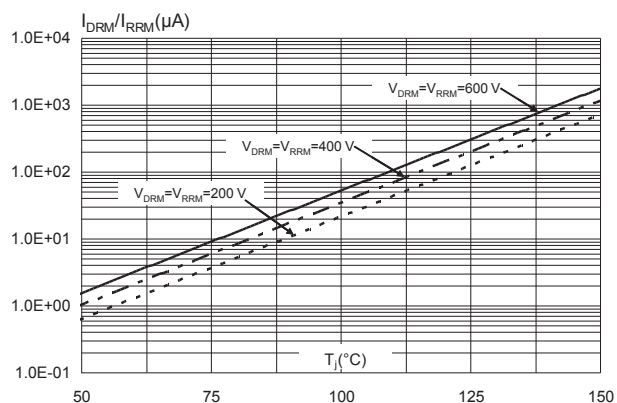
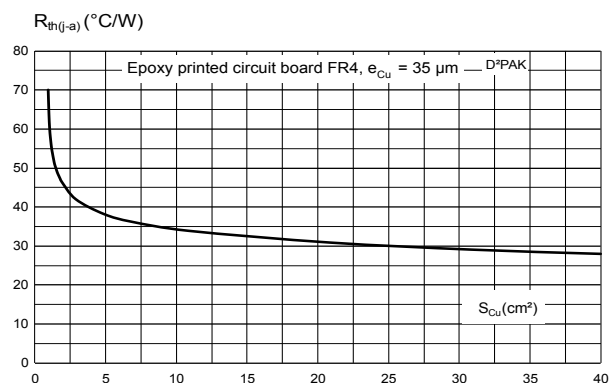


Figure 12. Thermal resistance junction to ambient versus copper surface under tab



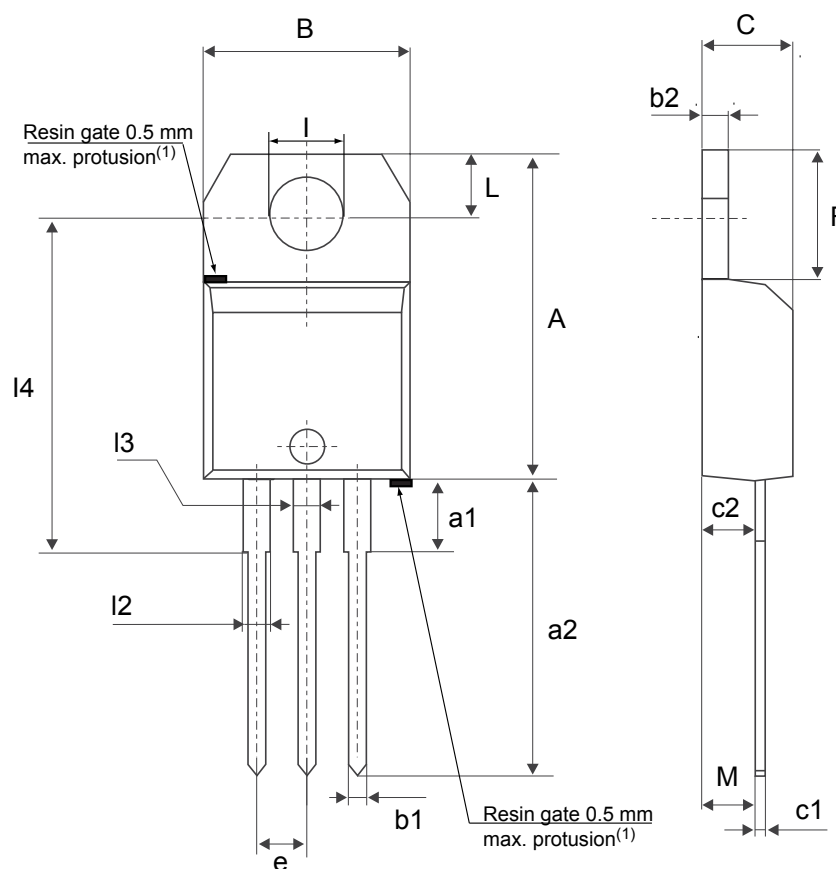
2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of **ECOPACK** packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

2.1 TO-220AB package information

- Molding compound resin is halogen-free and meets flammability standard UL94 level 0
- Lead-free package leads finishing
- **ECOPACK2** compliant
- Recommended torque: 0.4 to 0.6 N.m

Figure 13. TO-220AB package outline



(1) Resin gate position accepted in one of the two positions or in the symmetrical opposites.



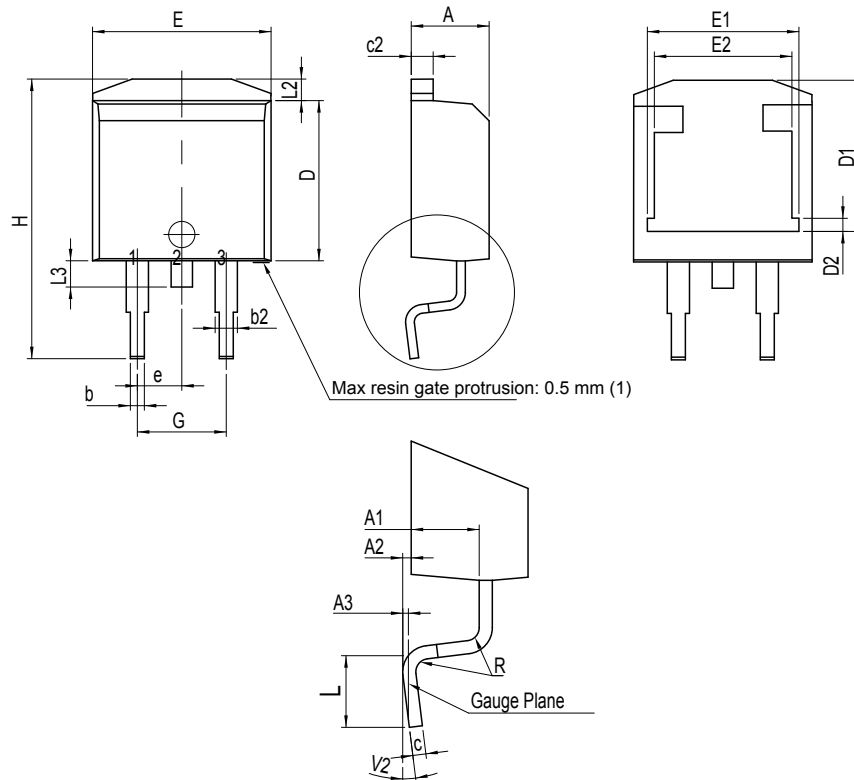
Table 5. TO-220AB package mechanical data

Ref.	Dimensions					
	Millimeters			Inches ⁽¹⁾		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	15.20		15.90	0.5984		0.6260
a1		3.75			0.1476	
a2	13.00		14.00	0.5118		0.5512
B	10.00		10.40	0.3937		0.4094
b1	0.61		0.88	0.0240		0.0346
b2	1.23		1.32	0.0484		0.0520
C	4.40		4.60	0.1732		0.1811
c1	0.49		0.70	0.0193		0.0276
c2	2.40		2.72	0.0945		0.1071
e	2.40		2.70	0.0945		0.1063
F	6.20		6.60	0.2441		0.2598
I	3.73		3.88	0.1469		0.1528
L	2.65		2.95	0.1043		0.1161
I2	1.14		1.70	0.0449		0.0669
I3	1.14		1.70	0.0449		0.0669
I4	15.80	16.40	16.80	0.6220	0.6457	0.6614
M		2.6			0.1024	

1. Inch dimensions are for reference only.

2.2 D²PAK package information

Figure 14. D²PAK package outline

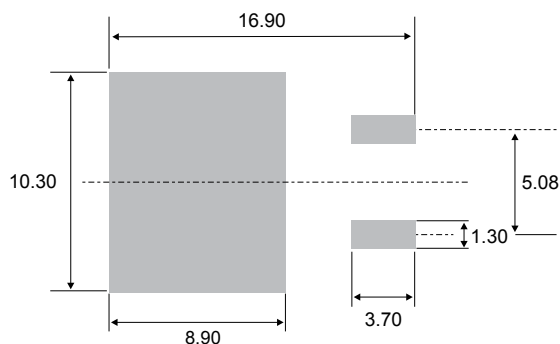


(1) Resin gate is accepted in each of position shown on the drawing, or their symmetrical.

Table 6. D²PAK package mechanical data

Ref.	Dimensions					
	Millimeters			Inches ⁽¹⁾		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.30		4.60	0.1693		0.1811
A1	2.49		2.69	0.0980		0.1059
A2	0.03		0.23	0.0012		0.0091
A3		0.25			0.0098	
b	0.70		0.93	0.0276		0.0366
b2	1.25		1.7	0.0492		0.0669
c	0.45		0.60	0.0177		0.0236
c2	1.21		1.36	0.0476		0.0535
D	8.95		9.35	0.3524		0.3681
D1	7.50		8.00	0.2953		0.3150
D2	1.30		1.70	0.0512		0.0669
e	2.54			0.1		
E	10.00		10.28	0.3937		0.4047
E1	8.30		8.70	0.3268		0.3425
E2	6.85		7.25	0.2697		0.2854
G	4.88		5.28	0.1921		0.2079
H	15		15.85	0.5906		0.6240
L	1.78		2.28	0.0701		0.0898
L2	1.27		1.40	0.0500		0.0551
L3	1.40		1.75	0.0551		0.0689
R		0.40			0.0157	
V2	0°		8°	0°		8°

1. Dimensions in inches are given for reference only

Figure 15. D²PAK recommended footprint (dimensions are in mm)


3 Ordering information

Figure 16. Ordering information scheme

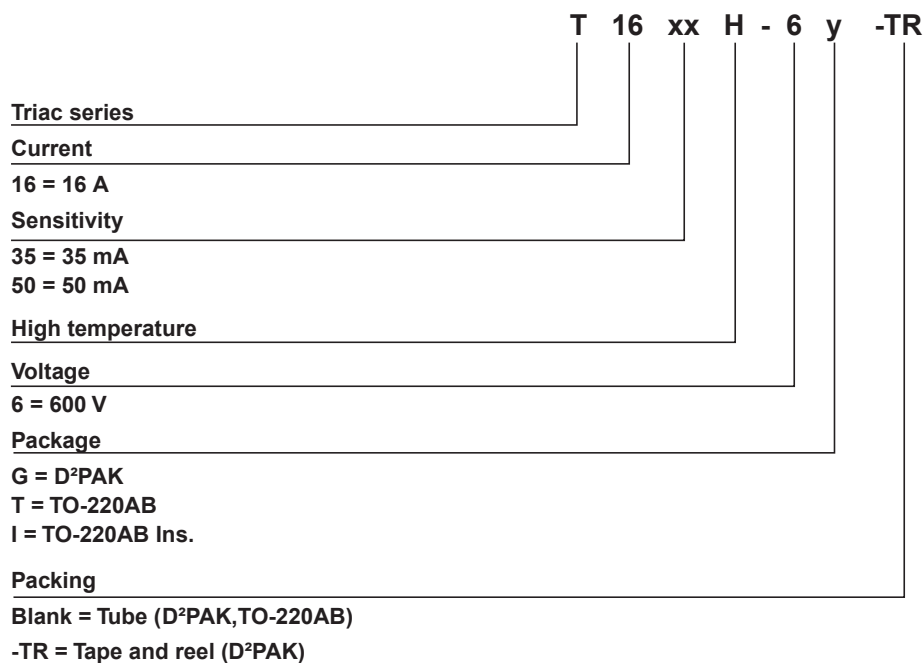


Table 7. Ordering information

Order code	Marking	Package	Weight	Base qty.	Delivery mode
T16xxH-6G	T16xxH 6G	D ² PAK	1.5 g	50	Tube
T16xxH-6G-TR				1000	Tape and reel 13"
T16xxH-6T	T16xxH 6T	TO-220AB	2.3 g	50	Tube
T16xxH-6I	T16xxH 6I	TO-220AB Ins.	2.3 g	50	Tube

Revision history

Table 8. Document revision history

Date	Version	Changes
29-May-2007	1	First issue.
20-Sep-2011	2	Updated: Features, Description and Figure 2.
31-Jan-2014	3	Updated Figure 2, Figure 3, Figure 4, Table 2 and Table 5.
23-Mar-2020	4	Updated Table 1. Absolute maximum ratings (limiting values) and Figure 3. On-state RMS current versus ambient temperature .



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